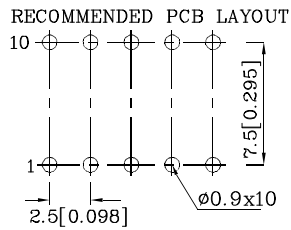
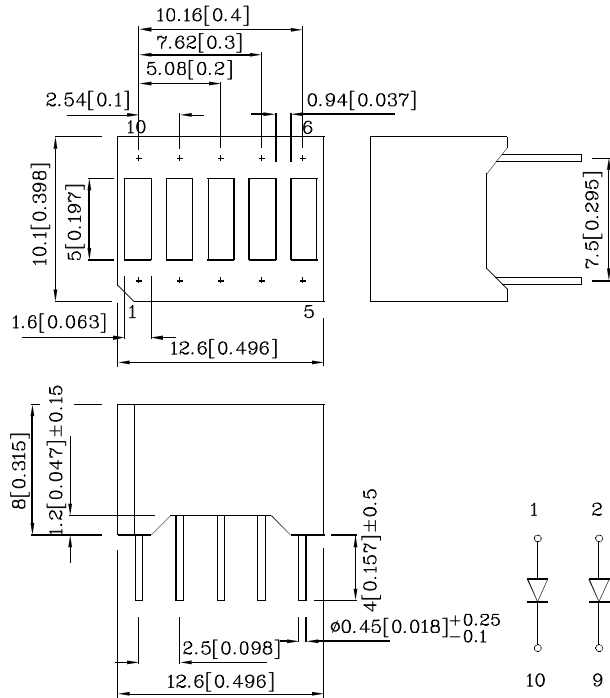


## Features

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- Standard configuration: Gray face w/ white segments
- RoHS compliant



## Package Schematics



### Notes:

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25$  (0.01") unless otherwise noted.
2. Specifications are subject to change without notice.

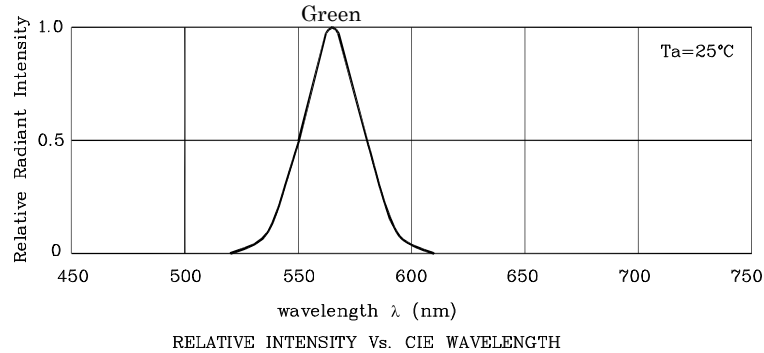
Absolute Maximum Ratings (T <sub>A</sub> =25°C)		Green (GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	140	mA
Power Dissipation	P <sub>D</sub>	62.5	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

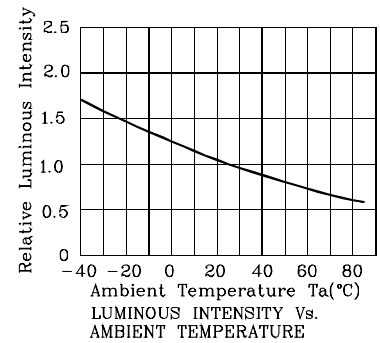
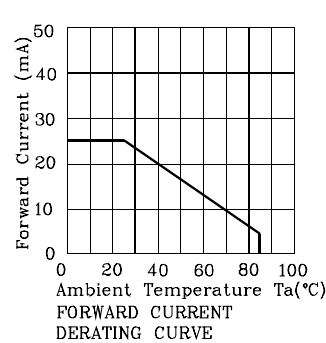
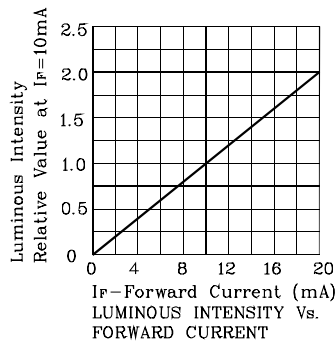
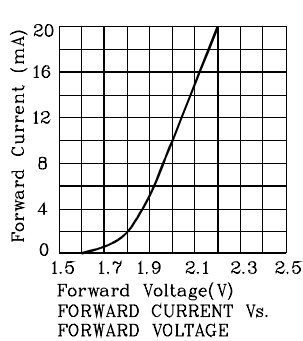
Operating Characteristics ( $T_A=25^\circ\text{C}$ )		Green (GaP)	Unit
Forward Voltage (Typ.) ( $I_F=10\text{mA}$ )	$V_F$	2	V
Forward Voltage (Max.) ( $I_F=10\text{mA}$ )	$V_F$	2.5	V
Reverse Current (Max.) ( $V_R=5\text{V}$ )	$I_R$	10	$\mu\text{A}$
Wavelength of Peak Emission CIE127-2007* (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_P$	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_D$	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ( $I_F=10\text{mA}$ )	$\Delta\lambda$	30	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	$C$	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* ( $I_F=10\text{mA}$ ) ucd		Wavelength CIE127-2007* nm $\lambda_P$	Description
			min.	typ.		
XGUGX5D	Green	GaP	5600 1400*	11990 3990*	565*	5 Segment Bar graph-Display

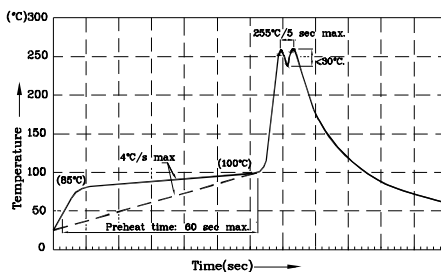
\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



## ❖ Green



## Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



### Notes:

- 1.Recommend pre-heat temperature of  $105^{\circ}\text{C}$  or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of  $260^{\circ}\text{C}$
- 2.Peak wave soldering temperature between  $245^{\circ}\text{C} \sim 255^{\circ}\text{C}$  for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above  $85^{\circ}\text{C}$ .
- 4.Pictures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.
- 7.During wave soldering, the PCB top-surface temperature should be kept below  $105^{\circ}\text{C}$ .

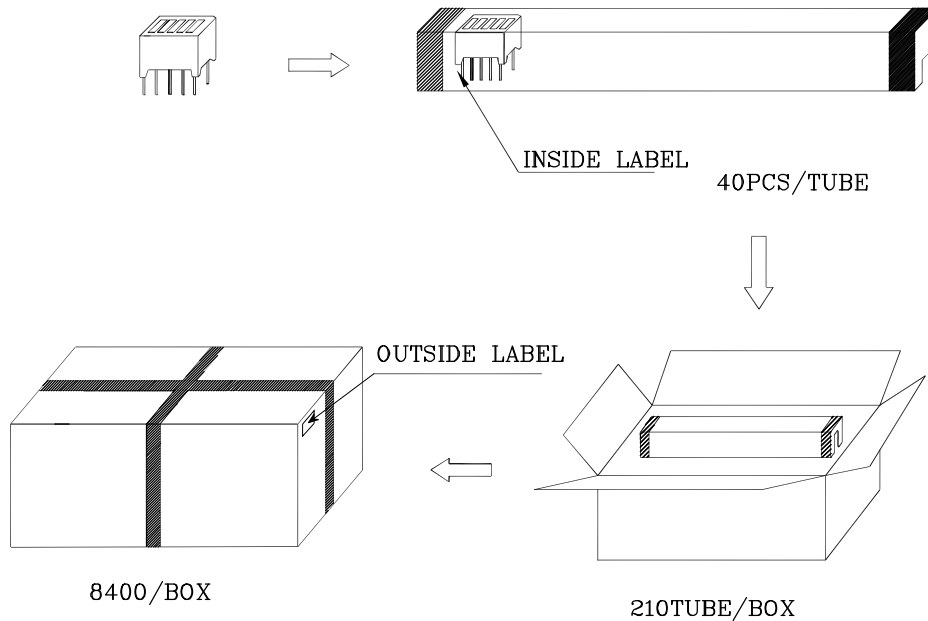
### Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

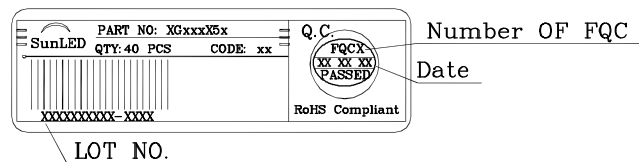
1. Wavelength:  $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux:  $\pm 15\%$
3. Forward Voltage:  $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

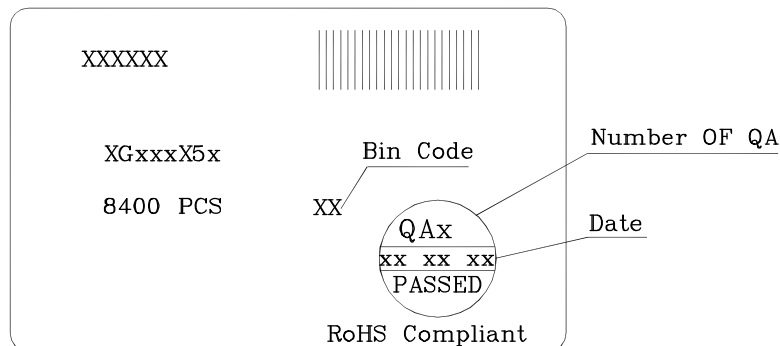
## PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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2. Contents within this document are subject to improvement and enhancement changes without notice.
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